

REMARKS

Applicants respectfully request consideration of the subject application as amended. Claims 1-24 have been withdrawn. Claims 25-41 and 44-57 are pending in the application. Claims 25, 29, 33, 35, 44 and 57 have been amended. Claims 41- 43 have been canceled. Claims 48-50 have been canceled without prejudice.

37 CFR 1.83(a) Drawing Objections

The drawings have been objected to under 37 CFR 1.83(a) for not showing one or more of a rivet, rod, staple, and wire through the first conductor and the second conductor to attach the first conductor to the second conductor.

Claim 57 has been amended to include the limitation "... disposing a plurality of small and sharp particles into the material used to make one of the first conductor and the second conductor to attach the first conductor to the second conductor." Applicant submits that the features in the claim are clearly shown in at least Figures 17A – 17C. Therefore, Applicants respectfully request the withdrawal of the objection to the drawings.

35 U.S.C. §112 first paragraph rejections

Claim 57 has been rejected under 35 U.S.C. §112, first paragraph, as failing to comply with the enablement requirement.

Claim 57 has been amended to include the limitation "... disposing a plurality of small and sharp particles into the material used to make one of the first conductor and the second conductor to attach the first conductor to the second conductor." Support for this limitation can be found in at least paragraphs [71 – 75] to enable a person skilled in the art to make and/or use the invention. Therefore, Applicants respectfully request the withdrawal of the rejection to the claim.

35 U.S.C. §112 second paragraph rejections

The Office Action has rejected claim 43 under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicants regard as the invention.

Claim 43 is canceled and therefore this rejection is now moot.

Claims 25 and 26 are rejected under 35 U.S.C. §102(e) as being anticipated by Zafrany, (U.S. Patent No. 6,677,186, hereinafter “Zafrany”).

Zafrany discloses a method for making an electronic device having an integrated circuit chip connected to an antenna (Abstract). Zafrany discloses a first conductor 12 formed on a chip 10. Zafrany intends for the “protrusions (first conductor) 12 to be embedded in the thickness of the antenna 6.” (Col. 4, lines 11-12).

Amended independent claim 25 includes the limitation “...the first conductor being interconnected to the second conductor by an anisotropic conductive medium ...” Zafrany fails to disclose such limitation. As such Applicants respectfully submit that amended independent claim 25 is not anticipated by Zafrany and respectfully request the withdrawal of the claim rejection.

Claim 26 directly depends from amended claim 25. For at least this reason, Zafrany fails to anticipate each and every element in claim 26 and Applicants respectfully request withdrawal of the claim rejection.

Claim 27 is rejected under 35 U.S.C. §103(a) as being unpatentable over Zafrany as applied to claim 25, and further in combination with Neuhaus, (US Patent No.: 6,853,087, hereinafter “Neuhaus”).

Neuhaus discloses a method of attaching physical and electrical conductive contacts of one component to a second component. Neuhaus teaches the use of electrically conductive hard particles upon conductive contacts of components and using non-conductive adhesive to provide permanent bond between conductors and their conductive pads (Figures 2-8). Neuhaus fails to teach or suggest the use of an anisotropic conductive medium between conductors.

Zafrany is described above and fails to disclose the use of an anisotropic conductive medium.

Claim 27 depends directly from amended Claim 25. For at least this reason, Applicants submit that claim 27 is patentable over Zafrany in view of Neuhaus. Therefore, Applicants respectfully request withdrawal of the claim rejection.

Claim 28 is rejected under 35 U.S.C. §103(a) as being unpatentable over Zafrany as applied to claim 25, and further in combination with Chang (US Patent Application 2003/0232174, hereinafter “Chang-P”).

Chang-P describes a series of steps to produce an LCD device but fails to teach or suggest the use of an anisotropic conductive medium between conductors. Zafrany is described above and also fails to disclose this limitation.

Claim 28 depends directly from amended Claim 25. For at least this reason, Applicants submit that the combination of Zafrany and Chang-P fails to teach or suggest

every element of the limitation in claim 28. Therefore, Applicants respectfully requests withdrawal of the claim rejection.

Claims 29, 30, 32, 35-40, and 45-47 are rejected under 35 U.S.C. §103(a) as being unpatentable over the combination of Zafrany and Zandman (US Patent Application 2001/0000631, hereinafter “Zandman”).

Zandman describes methods for semiconductor surface mount packaging. Zandman teaches the use of solder bumps, thermosetting polymers or thermoplastic polymers to form on the pads and portions of the metal layer to produce a completed package. Zandman does not teach or suggest the use of an anisotropic conductive medium between two conductors. Zafrany as described above also fails to disclose this limitation.

Independent claim 29

Amended independent claim 29 contains the limitation “...wherein an anisotropic conductive medium is attached to the first conductor ...” (Emphasis added).

Independent claim 35

Amended independent claim 35 contains the limitation “...the second conductor being electrically coupled to the first conductor via an anisotropic conductive medium ...” (Emphasis added).

As amended, both independent claims 29 and 35 contain the limitation of having an anisotropic conductive medium either attached to the first conductor or coupling the first and second conductors. The combination of Zafrany and Zandman does not teach or suggest this limitation. Therefore, Applicants respectfully submit that amended

independent claims 29 and 35 are patentable over Zafrany and Zandman and respectfully request withdrawal of the claim rejections.

Dependent claims 30, 32, 36-40 and 45-47

Dependent claims 30, 32, 36-40 and 45-47 either directly or indirectly depend from amended independent claims 29 and 35. For at least this reason, Applicant respectfully submits that they are also patentable over Zafrany in view of Zandman and respectfully requests withdrawal of the claim rejections.

Claim 31 is rejected under 35 U.S.C. §103(a) as being unpatentable over Zafrany and Zandman as applied to claim 29, and further in combination with Chang-P.

Zafrany, Chang-P, and Zandman are described above and none teaches or suggests the limitation of having an anisotropic conductive medium. Claim 31 directly depends from amended claim 29 and thus contains the amended limitation. For at least this reason, the combination of Zafrany, Chang-P and Zandman fails to teach or suggest the limitation as disclosed and Applicant respectfully requests withdrawal of the claim rejection.

Claims 33, 34, 41, 44 and 48-56 are rejected under 35 U.S.C. §103(a) as being unpatentable over Zafrany and Zandman as applied to claims 29 and 35, and further in combination with Neuhaus.

Zafrany, Zandman and Neuhaus are described above and none teaches or suggests the limitation of having an anisotropic conductive medium. Amended claim 33, and

claims 34, 41, 44 and 48-56 either directly or indirectly depends from the amended independent claims 29 and 35. For at least this reason, the combination of Zafrany and Zandman in view of Neuhaus fails to teach or suggest the amended limitation as incorporated and Applicant respectfully requests withdrawal of the claim rejection.

Claims 35 and 41 are rejected under 35 U.S.C. §103(a) as being unpatentable over Karpman (US Patent No.: 6,448,109, hereinafter “Karpman”) and Chang (US Patent No. 5707902, hereinafter “Chang-SM”).

Karpman discloses a wafer level method of capping multiple MEM elements. Specifically Karpman teaches disposing solder bumps between facing contact pads of the chip and the MEMS wafer for bonding. Karpman fails to teach or suggest the use of an anisotropic conductive medium.

Chang-SM similarly discloses the use of a solder coating on the composite bumps on the integrated circuit element or substrate for conduction. However, Chang-SM fails to teach or suggest the use of an anisotropic conductive medium.

Amended Independent claim 35

Amended independent claim 35 contains the limitation “...the second conductor being electrically coupled to the first conductor via an anisotropic conductive medium ...” (Emphasis added). As such, the combination of Karpman and Chang-SM fails to teach or suggest the amended limitation. Therefore, Applicant respectfully requests for the withdrawal of the claim rejection.

Dependent claim 41 has been cancelled and the claim rejection is now moot.

CONCLUSION

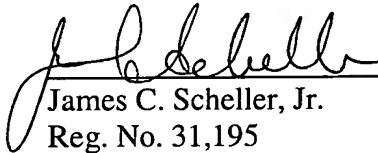
In conclusion, Applicant respectfully submits that in view of the amendments and arguments set forth, the applicable rejections have been overcome.

Please charge any shortages and credit any overcharges to our Deposit Account No. 02-2666.

Respectfully submitted,

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